

show files

File 347:JAPIO Dec 1976-2008/Oct(Updated 090220)
 (c) 2009 JPO & JAPIO
 File 350:Derwent WPIX 1963-2008/UD=200917
 (c) 2009 Thomson Reuters
 File 344:Chinese Patents Abs Jan 1985-2006/Jan
 (c) 2006 European Patent Office
 File 371:French Patents 1961-2002/BOPI 200209
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Set	Items	Description
S1	21	AU = (LEEDY G? OR LEEDY, G?)
S2	220679	3D? ? OR (THREE OR TRIAD OR TRI OR 3 OR TERNARY) ()DIMENSIO- N? OR TRIMENSION?
S3	1834918	IC? ? OR INTEGRATED ()CIRCUIT OR SEMI ()CONDUCT? OR SEMICOND- UCTOR?
S4	130585	(FIRST OR 1ST) (2N)SUBSTRATE?
S5	237210	(FIRST OR 1ST) (2N)SURFACE?
S6	6604	(INTER ()CONNECT? OR INTERCONNECT?) (2N)CONTACT?
S7	187716	SECOND (2N)SURFACE?
S8	11026	(HEAT OR TEMPERATURE OR THERMAL) (2N)DIFFUSION?
S9	2988597	BOND OR CONNECTION OR CONNECT? ? OR BONDED OR INFUSED
S10	13617	CONDUCTIVE (2N) (PATH? ? OR CHANNEL? ? OR CONDUIT? OR LANE? ? OR TRAIL? ?)
S11	2737121	THICK OR THICKNESS OR DIMENSION OR MEASUREMENT OR WIDE OR - BREADTH OR LENGTH
S12	273787	OVERLAP??????? OR OVER ()LAP???????
S13	2042918	S2 OR S3
S14	18	S13 AND S1
S15	6	S14 AND PY<=1997
S16	13014	S13 AND S4 AND S7
S17	27621	S13 AND S4 AND SECOND (2N) SUBSTRATE?
S18	9659	S17 AND S5
S19	156	S8 (3N) S9
S20	2	S18 AND S19
S21	453	S17 AND S6
S22	64	S11 AND S21
S23	64	S22 NOT S20
S24	1491	S4 (6N) S11
S25	402	S24 AND S17
S26	96	S25 AND S9
S27	4	S26 AND S12
S28	4	S27 NOT S15
S29	0	S13 AND S6 AND S8 AND S9 AND S10 AND S12
S30	17	S8 AND S10 AND S13
S31	7	S30 AND SECOND (2N) SUBSTRATE?

EAST Search History

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	1	"20040070063".pn.	US-PGPUB; USPAT	OR	ON	2009/03/26 13:13
L2	1115448	bonding or bonded or bond	US-PGPUB; USPAT	OR	ON	2009/03/26 13:39
L3	175444	(first or second or 1st or 2nd) near substrate	US-PGPUB; USPAT	OR	ON	2009/03/26 13:40
L4	74190	2 and 3	US-PGPUB; USPAT	OR	ON	2009/03/26 13:41
L5	908938	interconnect\$ or inter-connect\$ or inter adj connect\$	US-PGPUB; USPAT	OR	ON	2009/03/26 13:42
L6	21271	4 and 5	US-PGPUB; USPAT	OR	ON	2009/03/26 13:42
L7	12706	6 and ("257"/\$.cccls. or "438"/\$.cccls.)	US-PGPUB; USPAT	OR	ON	2009/03/26 13:43
L8	134955	(bonding or bonded or bond)[ti,ab]	US-PGPUB; USPAT	OR	ON	2009/03/26 13:44
L9	31002	((first or second or 1st or 2nd) near substrate)[ti,ab]	US-PGPUB; USPAT	OR	ON	2009/03/26 13:44
L10	2886	8 and 9	US-PGPUB; USPAT	OR	ON	2009/03/26 13:44
L11	926	5 and 10	US-PGPUB; USPAT	OR	ON	2009/03/26 13:44
L12	112428	(interconnect\$ or inter-connect\$ or inter adj connect\$)[ti,ab]	US-PGPUB; USPAT	OR	ON	2009/03/26 13:45
L13	251	10 and 12	US-PGPUB; USPAT	OR	ON	2009/03/26 13:45
L14	786314	bonding or bonded or bond	FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/03/26 14:22
L15	48025	(first or second or 1st or 2nd) near substrate	FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/03/26 14:22
L16	5403	14 and 15	FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/03/26 14:22
L17	242393	interconnect\$ or inter-connect\$ or inter adj connect\$	FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/03/26 14:23

EAST Search History

L18	373	16 and 17	FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/03/26 14:23
L19	8801	(heat or thermal or temperature) near diffusion	FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/03/26 14:24
L20	3	18 and 19	FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/03/26 14:25
L21	2526689	thick or thinkness or dimension or measurement or wide or breadth or length	FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/03/26 14:26
L22	89	18 and 21	FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/03/26 14:26
L23	482	15 near6 21	FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/03/26 14:28
L24	6	23 and 18	FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/03/26 14:28
L25	4315	(first near substrate) and 21	FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/03/26 14:30
L26	8875	(twice or double) near3 21	FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/03/26 14:31
L27	9	(first near substrate) and 26	FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/03/26 14:31

File 2:INSPEC 1898-2009/Mar W3
 (c) 2009 Institution of Electrical Engineers
 File 6:NTIS 1964-2009/Mar W5
 (c) 2009 NTIS, Intl Cpyrght All Rights Res
 File 8:EI Compendex(R) 1884-2009/Mar W3
 (c) 2009 Elsevier Eng. Info. Inc.
 File 25:Weldasearch 1966-2009/Mar
 (c) 2009 TWI Ltd
 File 36:MetalBase 1965-20090326
 (c) 2009 The Thomson Corporation
 File 65:Inside Conferences 1993-2009/Mar 24
 (c) 2009 BLDSC all rts. reserv.
 File 92:IHS Intl.Stds.& Specs. 1999/Nov
 (c) 1999 Information Handling Services
 File 95:TEME-Technology & Management 1989-2009/Feb W4
 (c) 2009 FIZ TECHNIK
 File 99:Wilson Appl. Sci & Tech Abs 1983-2009/Feb
 (c) 2009 The HW Wilson Co.
 File 103:Energy SciTec 1974-2009/Mar B1
 (c) 2009 Contains copyrighted material
 File 104:AeroBase 1999-2009/Mar
 (c) 2009 Contains copyrighted material
 File 144:Pascal 1973-2009/Mar W3
 (c) 2009 INIST/CNRS
 File 239:Mathsci 1940-2009/Apr
 (c) 2009 American Mathematical Society
 File 47:Gale Group Magazine DB(TM) 1959-2009/Mar 17
 (c) 2009 Gale/Cengage
 File 315:ChemEng & Biotec Abs 1970-2009/Mar
 (c) 2009 DECHEMA
 File 31:World Surface Coatings Abs 1976-2009/Jan
 (c) 2009 PRA Coat. Tech. Cen.
 File 248:PIRA 1975-2009/Mar W3
 (c) 2009 Pira International
 File 23:CSA TECHNOLOGY RESEARCH DATABASE 1963-2009/MAR
 (c) 2009 CSA.
 File 46:CORROSION ABSTRACTS 1966-2009/MAR
 (c) 2009 CSA.
 File 68:Solid State & Superconductivity Abstracts 1966-2009/Mar
 (c) 2009 CSA.
 File 60:ANTE: Abstracts in New Tech & Engineer 1966-2009/Mar
 (c) 2009 CSA.
 File 33:Aluminium Industry Abstracts 1966-2009/Mar
 (c) 2009 CSA.
 File 335:CERAMIC ABSTRACTS/WORLD CERAMICS ABSTRACTS 1966-2009/MAR
 (c) 2009 CSA.
 File 294:ONTAP(R) SciSearch(R) Cited Ref Science
 (c) 2006 The Thomson Corp
 File 954:EI EnCompassLit(TM) 1965-2009/Mar W4
 (c) 2009 Elsevier Eng. Info. Inc.
 File 953:EI EnCompassPat(TM) 1964-200859
 (c) 2009 Elsevier Eng. Info. Inc.

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Set	Items	Description
S1	1457807	3D? ? OR (THREE OR TRIAD OR TRI OR 3 OR TERNARY) {}DIMENSIO- N? OR TRIMENSION?

S2 3579838 IC? ? OR INTEGRATED()CIRCUIT OR SEMI()CONDUCT? OR SEMICOND-
 UCTOR?
 S3 20351 (FIRST OR 1ST) (2N)SUBSTRATE?
 S4 52593 (FIRST OR 1ST) (2N)SURFACE?
 S5 5340 (INTER()CONNECT? OR INTERCONNECT?) (2N)CONTACT?
 S6 11249 SECOND(2N)SUBSTRATE?
 S7 120309 (HEAT OR TEMPERATURE OR THERMAL) (2N)DIFFUSION?
 S8 1803510 BOND OR CONNECTION OR CONNECT? ? OR BONDED OR INFUSED
 S9 6963 CONDUCTIVE(2N) (PATH? ? OR CHANNEL? ? OR CONDUIT? OR LANE? ?
 OR TRAIL? ?)
 S10 13803070 THICK OR THINKNESS OR DIMENSION? OR MEASUREMENT? OR WIDE OR
 BREADTH OR LENGTH
 S11 322146 OVERLAP??????? OR OVER()LAP???????
 S12 4964022 S1 OR S2
 S13 9726 S12 AND (S3 OR S6)
 S14 65 S5 AND S13
 S15 0 S14 AND S7 AND S8
 S16 15 S14 AND (S7 OR S8)
 S17 5 S16 AND (S9 OR S10 OR S11)
 S18 3 RD (unique items)
 S19 13 S3 AND (TWICE OR DOUBLE) (3N)S10
 S20 4 RD S19 (unique items)
 S21 4 S20 NOT S18
 S22 10 S7 AND S9
 S23 7 RD (unique items)
 S24 0 S23 AND S11

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3/27/2009 4:12:50 PM

3/27/2009 4:59:25 PM

[File 2] INSPEC 1898-2006/Jan W2
 [File 6] NTIS 1964-2006/Jan W4
 [File 8] Ei Compendex(R) 1970-2006/Jan W4
 [File 34] SciSearch(R) Cited Ref Sci 1990-2006/Jan W4
 [File 434] SciSearch(R) Cited Ref Sci 1974-1989/Dec
 [File 35] Dissertation Abs Online 1861-2006/Jan
 [File 65] Inside Conferences 1993-2006/Jan W5
 [File 99] Wilson Appl. Sci & Tech Abs 1983-2006/Apr
 [File 144] Pascal 1973-2006/Jan W2
 [File 23] CSA Technology Research Database 1963-2006/Jan
 [File 103] Energy SciTec 1974-2006/Jan B1
 [File 31] World Surface Coatings Abs 1976-2006/Jan
 [File 95] TEMA-Technology & Management 1989-2006/Jan W5
 [File 60] ANTE: Abstracts in New Tech & Engineer 1966-2006/Jan
 [File 293] Engineered Materials Abstracts 1966-2006/Jan
 [File 239] Mathsci 1940-2005/Feb
 [File 256] TECINPOUSOURCE 82-2005/DEC

Set Items Description

S1 5128338 S SEMICONDUCTOR OR SEMI()CONDUCTOR OR INTEGRATED()CIRCUIT???? OR IC OR CIRCUIT???? OR CHIP??? OR MICROCHIP???? OR MICROCIRCUIT????

S2 804146 S (3D OR 3()D OR (3 OR THREE OR THIRD)(2N)DIMENSION????) (3N) (DEVICE???? OR UNIT???? OR MODULE???? OR STRUCTURE??? OR MEANS OR ASSEMBL???? OR MEMOR????) OR DRAM OR SRAM OR FLASH OR EPROM OR EEPROM OR FERROELECTRIC OR FERRO()ELECTRIC OR MAGNETORESISTANCE??? OR MAGNETO()RESISTANCE???

S3 3584975 S (PLURAL???? OR MANY OR MORE OR SEVERAL???? OR MULTI???? OR DIFFER???? OR NUMBER??? OR NUMEROUS OR VARI???? OR VARY???? OR SET OR SETS OR ARRAY??? OR CLUSTER???? OR NETWORK???? OR TWO OR BOTH OR DIFFER???? OR PAIR???? OR COUPL???? OR DOUBLE??? OR DUAL???? OR TWIN OR ANOTHER OR SECOND???? OR 2 OR EACH) (3N) (LAYER??? OR MATERIAL???? OR SUBSTRATE???? OR SUBSTANCE??? OR MASK??? OR DEPOSIT?? OR SURFACE???)

S4 153128 S (INTERCONNECT???? OR CONNECT???? OR LINK???? OR COUPL????) (3N) (CONTACT???? OR POINT???? OR NODE???)

S5 90139 S (THERMAL???? OR THERMODIFFUS???? OR DIFFUSION) (3N) (SOLDER???? OR BOND??? OR ADHE???? OR CEMENT??? OR PAST???)

S6 5532804 S (TWICE OR TWO OR 2 OR TIMES OR GREATER OR LARGE???? OR THICK???? OR WIDE???? OR BROAD??? OR MAJOR??? OR COMPLETELY OR ENTIRE??? OR THOROUGHLY OR WHOL???? OR MAX OR MAXIMUM OR ALL OR TOTAL??? OR OVERLAP??? OR OVERLIE??? OR GREATER()THAN OR AT()LEAST OR MORE()THAN OR MAXIMUM OR AT()MOST OR SIZE??? OR DIMENSION???) (3N) (LAYER??? OR MATERIAL???? OR SUBSTRATE??? OR SUBSTANCE??? OR MASK??? OR DEPOSIT?? OR SURFACE?? OR 0()5 OR 0()05 OR 10 OR CENTIMET??? OR MILLIMET??? OR MICROMETE??? OR MM OR CM)

S7 4187715 S (OPTIM???? OR EFFECT???? OR EFFICIEN???? OR ACCURA???? OR MAXIM???? OR BETTER OR EXCEL???? OR IMPROV???? OR INCREASE??? OR HIGH OR HIGHER OR ENHANCE??? OR GOOD OR QUALITY??? OR AUGMENT???? OR BOOST???? OR RAISE????) (3N) (MEMORY()DENSITY OR PERFORM???? OR FUNCTION??? OR OPERATION??? OR DESIGN???)

S8 1055976 S (MINIM???? OR LOWER???? OR LOW OR REDUC???? OR ATTENUAT???? OR DECREASE???? OR LESS???? OR LIMIT??? OR MITIGAT???? OR DIMINISH??? OR RELAX????) (3N) (COST??? OR MEGABYTE???)

S9 0 S S1 AND S2 AND S3 AND S4 AND S5 AND S6 AND S7 AND S8

S10 6734 S S1 AND S2 AND S3 AND S6

S11 57 S S10 AND S4

S12 0 S S11 AND S5

S13 10 S S11 AND S7

S14 5 RD (unique items)

S15 0 S S11 AND S8

S16 917 S S1(3N)S2(3N)S6

S17 344 S S16 AND S3

S18 4 S S17 AND S4

S19 2 RD (unique items)

S20 1 S S17 AND S5

S21 39 S S17 AND S7

3/27/2009 4:12:50 PM

3/27/2009 4:59:25 PM

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S22      5  S S21 AND S8
S23      5  RD (unique items)
S24      7296 S S2(3N)S3(3N)S6
S25      1419 S S24 AND S1
S26      14  S S25 AND S4
S27      6  RD (unique items)
S28      4  S S25 AND S5
S29      1  RD (unique items)
S30      121 S S25 AND S7
S31      7  S S30 AND S8
S32      7  RD (unique items)
S33      206 S S2(3N)S6(3N)S7
S34      87  S S33 AND S1
S35      23  S S34 AND S3
S36      14  RD (unique items)
S37      1  S S34 AND S4
S38      4  S S34 AND S5
S39      1  RD (unique items)
S40      1  S S34 AND S8
S41      25  S S2(3N)S6(3N)S8
S42      14  RD (unique items)
S43      2  S S19 NOT S14
S44      1  S S20 NOT (S14 OR S19)
S45      5  S S23 NOT (S14 OR S19 OR S20)
S46      3  S S27 NOT (S14 OR S19 OR S20 OR S23)
S47      1  S S29 NOT (S14 OR S19 OR S20 OR S23 OR S27)
S48      4  S S32 NOT (S14 OR S19 OR S20 OR S23 OR S27 OR S29)
S49      11  S S36 NOT (S14 OR S19 OR S20 OR S23 OR S27 OR S29 OR S32)
S50      0  S S37 NOT (S14 OR S19 OR S20 OR S23 OR S27 OR S29 OR S32 OR S36)
S51      0  S S39 NOT (S14 OR S19 OR S20 OR S23 OR S27 OR S29 OR S32 OR S36 OR S37)

S52      0  S S40 NOT (S14 OR S19 OR S20 OR S23 OR S27 OR S29 OR S32 OR S36 OR S37 OR
S39)

S53      14  S S42 NOT (S14 OR S19 OR S20 OR S23 OR S27 OR S29 OR S32 OR S36 OR S37 OR
S39 OR S40)

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(FILE 'HOME' ENTERED AT 16:16:51 ON 27 MAR 2009)

FILE 'CAPLUS, KOREAPAT' ENTERED AT 16:17:09 ON 27 MAR 2009

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L1      1003139 SEA SPE=ON ABB=ON PLU=ON SEMICONDUCTOR OR SEMI CONDUCTOR OR
        IC OR INTEGRATED CIRCUIT OR CHIP OR MICROCHIP OR MICROCIRCUIT###
        ###
L2      265786 SEA SPE=ON ABB=ON PLU=ON (3D OR 3 D OR (THREE OR THIRD OR
        3) (3A) DIMENSION#####) (3A) (DEVICE OR UNIT OR MODUL#### OR
        STRUCTURE OR MEANS OR ASSEMBL#### OR MEMOR#####) OR DRAM OR
        SRAM OR FLASH OR EPROM OR EEPROM OR FERROELECTRIC OR FERRO
        ELECTRIC OR MAGNETORESISTAN### OR MAGNETO RESISTAN####
L3      1073229 SEA SPE=ON ABB=ON PLU=ON (PLURAL##### OR MULTI##### OR
        SEVERAL#### OR DIFFER##### OR TWO OR BOTH OR PAIR#### OR
        COUPL#### OR DOUBL##### OR DUAL#### OR ANOTHER OR SECONDD####
        OR 2 OR EACH) (3A) (LAYER OR MATERIAL OR SUBSTRATE OR SUBSTANCE
        OR SURFACE)
L4      1184188 SEA SPE=ON ABB=ON PLU=ON (TWICE OR TWO OR 2 OR TIMES OR
        GREATER OR LARGER OR THICK##### OR WIDE##### OR BROAD#####
        OR GREATER THAN OR AT LEAST OR MORE THAN OR MAXIMUM OR AT MOST
        OR SIZE OR DIMENSION) (3A) (LAYER OR MATERIAL OR SUBSTRATE OR
        SUBSTANCE OR MM OR MILLIMET#### OR CENTIMET### OR CM OR
        MICROMET###)
L5      50 SEA SPE=ON ABB=ON PLU=ON MEMORY DENSITY
L6      1886 SEA SPE=ON ABB=ON PLU=ON L1 AND L2 AND L3 AND L4
L7      48 SEA SPE=ON ABB=ON PLU=ON L1 (3A) L2 (3A) L4
L8      29 SEA SPE=ON ABB=ON PLU=ON L7 AND L3
L9      29 DUP REM L8 (0 DUPLICATES REMOVED)
L10     6 SEA SPE=ON ABB=ON PLU=ON L9 NOT PY>1997
L11     0 SEA SPE=ON ABB=ON PLU=ON L8 AND L5
L12     104055 SEA SPE=ON ABB=ON PLU=ON L3 (3A) L4
L13     1 SEA SPE=ON ABB=ON PLU=ON L12 AND L5
L14     14459 SEA SPE=ON ABB=ON PLU=ON L12 AND L1
L15     199 SEA SPE=ON ABB=ON PLU=ON L12 (3A) L2
L16     33609 SEA SPE=ON ABB=ON PLU=ON (THERMAL#### OR THERMODIFFUS#####
        OR DIFFUS#####) (3A) (SOLDER#### OR BOND#### OR ADHE##### OR
        CEMENT#### OR PAST####)
L17     0 SEA SPE=ON ABB=ON PLU=ON L9 AND L16
L18     480 SEA SPE=ON ABB=ON PLU=ON L14 AND L2
L19     5 SEA SPE=ON ABB=ON PLU=ON L18 AND L16
L20     0 SEA SPE=ON ABB=ON PLU=ON L6 AND L5
L21     8 SEA SPE=ON ABB=ON PLU=ON L6 AND L16
L22     665 SEA SPE=ON ABB=ON PLU=ON L2 (3A) L3 (3A) L4
L23     0 SEA SPE=ON ABB=ON PLU=ON L22 AND L5
L24     1 SEA SPE=ON ABB=ON PLU=ON L22 AND L16
L25     106 SEA SPE=ON ABB=ON PLU=ON L22 AND L1
L26     0 SEA SPE=ON ABB=ON PLU=ON L2 (3A) L3 (3A) L5
L27     0 SEA SPE=ON ABB=ON PLU=ON L2 (3A) L3 (3A) L16
L28     0 SEA SPE=ON ABB=ON PLU=ON L2 (3A) L4 (3A) L5
L29     2 SEA SPE=ON ABB=ON PLU=ON L2 AND L3 AND L5
L30     1886 SEA SPE=ON ABB=ON PLU=ON L2 AND L3 AND L6
L31     0 SEA SPE=ON ABB=ON PLU=ON L2 AND L4 AND L5
L32     41 SEA SPE=ON ABB=ON PLU=ON L2 AND L3 AND L16
L33     21 SEA SPE=ON ABB=ON PLU=ON L32 AND L4
L35     4 SEA SPE=ON ABB=ON PLU=ON L34 NOT PY>1997
L36     0 SEA SPE=ON ABB=ON PLU=ON L32 AND L5
L37     17 SEA SPE=ON ABB=ON PLU=ON L32 AND L1
L38     17 DUP REM L37 (0 DUPLICATES REMOVED)
L39     0 SEA SPE=ON ABB=ON PLU=ON L38 NOT PY>1997

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      D L10 IBIB ABS 1-6
      D L13 IBIB ABS
L40    5 SEA SPE=ON  ABB=ON  PLU=ON  L19 NOT (L10 OR L13)
      D L40 IBIB ABS 1-5
L41    3 SEA SPE=ON  ABB=ON  PLU=ON  L21 NOT (L10 OR L13 OR L19)
      D L41 IBIB ABS 1-3
L42    1 SEA SPE=ON  ABB=ON  PLU=ON  L24 NOT (L10 OR L13 OR L19 OR L21)

      D L42 IBIB ABS
L43    2 SEA SPE=ON  ABB=ON  PLU=ON  L29 NOT (L10 OR L13 OR L19 OR L21
      OR L24)
      D L43 IBIB ABS
      D L43 IBIB ABS 1-2
L44    4 SEA SPE=ON  ABB=ON  PLU=ON  L35 NOT (L10 OR L13 OR L19 OR L21
      OR L24 OR L29)
      D L44 IBIB ABS 1-4
L45    9 SEA SPE=ON  ABB=ON  PLU=ON  L38 NOT (L10 OR L13 OR L19 OR L21
      OR L24 OR L29 OR L35)
      D L45 IBIB ABS 1-9
FILE 'STNGUIDE' ENTERED AT 16:44:02 ON 27 MAR 2009
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3/27/2009 5:22:38 PM

3/27/2009 6:01:22 PM

[File 344] Chinese Patents Abs Jan 1985-2006/Jan
 [File 347] JAPIO Dec 1976-2008/Oct(Updated 090220)
 [File 350] Derwent WPIX 1963-2008/UD-200913
 [File 371] French Patents 1961-2002/BOPI 200209

Set Items Description

S1 4389304 S SEMICONDUCTOR OR SEMI() CONDUCTOR OR INTEGRATED() CIRCUIT???? OR IC OR CIRCUIT???? OR CHIP??? OR MICROCHIP???? OR MICROCIRCUIT????

S2 352212 S (3D OR 3()) D OR (3 OR THREE OR THIRD) (2N) DIMENSION???? (3N) (DEVICE???? OR UNIT???? OR MODULE???? OR STRUCTURE??? OR MEANS OR ASSEMBL???? OR MEMOR???? OR DRAM OR SRAM OR FLASH OR EPROM OR EEPROM OR FERROELECTRIC OR FERRO() ELECTRIC OR MAGNETORESISTANC???? OR MAGNETO() RESISTANC???

S3 2906394 S (PLURAL???? OR MANY OR MORE OR SEVERAL???? OR MULTI???? OR DIFFER???? OR NUMBER???? OR NUMEROUS OR VARI?????? OR VARY???? OR SET OR SETS OR ARRAY??? OR CLUSTER???? OR NETWORK???? OR TWO OR BOTH OR DIFFER???? OR PAIR??? OR COUPL???? OR DOUBLE??? OR DUAL???? OR TWIN OR ANOTHER OR SECOND????? OR 2 OR EACH) (3N) (LAYER??? OR MATERIAL???? OR SUBSTRATE???? OR SUBSTANCE??? OR MASK??? OR DEPOSIT?? OR SURFACT??)

S4 328872 S (INTERCONNECT???? OR CONNECT???? OR LINK?????? OR COUPL????) (3N) (CONTACT???? OR POINT???? OR NODE???)

S5 33871 S (THERMAL???? OR THERMODIFFUS???? OR DIFFUSION) (3N) (SOLDER???? OR BOND??? OR ADHE?????? OR CEMENT??? OR PAST?????)

S6 3400683 S (TWICE OR TWO OR 2 OR TIMES OR GREATER OR LARGE????? OR THICK????? OR WIDE????? OR BROAD????? OR MAJOR????? OR COMPLETELY OR ENTIRE????? OR THOROUGHLY OR WHOL????? OR MAX OR MAXIMUM OR ALL OR TOTAL????? OR OVERLAP????? OR OVERLIE????? OR GREATER() THAN OR AT() LEAST OR MORE() THAN OR MAXIMUM OR AT() MOST OR SIZE??? OR DIMENSION????) (3N) (LAYER??? OR MATERIAL???? OR SUBSTRATE???? OR SUBSTANCE??? OR MASK??? OR DEPOSIT?? OR SURFACT??? OR 0() 5 OR 0() 105 OR 10 OR CENTIMET??? OR MILLIMET??? OR MICROMETE????? OR MM OR CM)

S7 1286707 S (OPTIM????? OR EFFECT????? OR EFFICIEN????? OR ACCURA????????? OR MAXIM????? OR BETTER OR EXCEL????? OR IMPROV????????? OR INCREASES????? OR HIGH OR HIGHER OR ENHANC????? OR GOOD OR QUALITY????? OR AUGMENT????????? OR BOOST??????? OR RAISE????????) (3N) (MEMORY() DENSITY OR PERFORM??????? OR FUNCTION??? OR OPERATION??? OR DESIGN?????)

S8 1085807 S (MINIM????????? OR LOWER????? OR LOW OR REDUC????????? OR ATTENUAT????? OR DECREASES????? OR LESS????? OR LIMIT????? OR MITIGAT????????????? OR DIMINISH??? OR RELAX?????) (3N) (COST??? OR MEGABYTE????)

S9 82930 S MC=(U13-C04B1A OR U13-C04B1B OR U13-C04B2 OR U14-A03B1 OR U14-A03B4 OR U14-A03B7 OR U14-A03F OR U14-A04A OR U14-C)

S10 1 S S1 AND S2 AND S3 AND S4 AND S5 AND S6 AND S7 AND S8

S11 1029 S S1(3N) S2(3N) S3(3N) S6

S12 112 S S11 AND S4

S13 0 S S12 AND S5

S14 8 S S12 AND S7

S15 5 S S12 AND S8

S16 73 S S12 AND S9

S17 94 S S2(3N) S6(3N) S7

S18 42 S S17 AND S1

S19 38 S S18 AND S3

S20 5 S S19 AND S4

S21 0 S S19 AND S5

S22 2 S S19 AND S8

S23 19 S S19 AND S9

S24 47 S S2(3N) S6(3N) S8

S25 18 S S24 AND S1

S26 12 S S25 AND S3

S27 1 S S25 AND S4

S28 2 S S25 AND S5

S29 4 S S25 AND S7

S30 4 S S25 AND S9

S31 9 S S2(3N) S5(3N) S6

3/27/2009 5:22:38 PM

3/27/2009 6:01:22 PM

S32 5 S S15 NOT S14
 S33 5 S S20 NOT (S14 OR S15)
 S34 1 S S22 NOT (S14 OR S15 OR S20)
 S35 11 S S26 NOT (S14 OR S15 OR S20 OR S22)
 S36 1 S S27 NOT (S14 OR S15 OR S20 OR S22 OR S26)
 S37 0 S S28 NOT (S14 OR S15 OR S20 OR S22 OR S26 OR S27)
 S38 0 S S29 NOT (S14 OR S15 OR S20 OR S22 OR S26 OR S27 OR S28)
 S39 0 S S30 NOT (S14 OR S15 OR S20 OR S22 OR S26 OR S27 OR S28 OR S29)
 S40 8 S S31 NOT (S14 OR S15 OR S20 OR S22 OR S26 OR S27 OR S28 OR S29 OR S30)

 S41 5 S S25 NOT (S14 OR S15 OR S20 OR S22 OR S26 OR S27 OR S28 OR S29 OR S30 OR
 S31)

 S42 18 S S23 NOT (S14 OR S15 OR S20 OR S22 OR S25 OR S26 OR S27 OR S28 OR S29 OR
 S30 OR S31)

(FILE 'HOME' ENTERED AT 09:52:30 ON 22 APR 2009)

FILE 'HCAPLUS, WPIX, JAPIO, KOREAPAT' ENTERED AT 09:53:43 ON 22 APR 2009

L1 1205438 SEA ((INTEGRATED(2A) CIRCUIT####) OR IC OR (CIRCUIT### OR WIRE
OR WIRING)(2A) BOARD## OR PRINTED(2A) (CIRCUIT#### OR BOARD##)
OR PCB OR PWB OR PCA OR MOTHERBOARD)

L2 3540433 SEA (THICK#### OR THIN#### OR SLIM####)

L3 79716 SEA L2(5A) (TWICE OR DOUBLE OR TWO OR HALF OR TWOFOLD##)

L4 1968391 SEA (SUBSTRATE### OR SURFACE### OR MEMBRANE## OR WAFER## OR
CHIP## OR MICROCHIP## OR DIE OR DIES OR DICE####) (6A) (FIRST OR
ONE OR 1ST OR PRIMARY OR SECOND OR TWO OR 2ND OR OTHER OR
SECONDARY)

L5 1278 SEA L1 AND L3 AND L4

L6 471 SEA L1 AND L3(5A) L4

L7 214 SEA L6 AND SUBSTRATE##(5A) (THICK#### OR THIN#### OR SLIM####)

L8 0 SEA L7 AND TWICE(3A) THICK###

L9 28 SEA L7 AND (SUBSTRATE## OR SURFACE####) (5A) (OVERLAP##### OR
COVER#####)

L10 6 SEA L9 NOT 1998-2009/PY, PRY

L11 21 SEA L7 AND L4(5A) (OVERLAP##### OR COVER####)

L12 3 SEA L11 NOT L9

L13 1 SEA L12 NOT 1998-2009/PY, PRY

L14 4 SEA L5 AND SUBSTRATE####(4A) (FIRST OR SECOND OR PRIMARY OR
SECONDARY OR 1ST OR 2ND) (4A) (THICK#### OR THIN#### OR SLIM####)
(4A) (TWICE OR DOUBLE OR HALF OR TWOFOLD###)

L15 4 SEA L14 NOT (L9 OR L11)

L16 0 SEA L15 NOT 1998-2009/PY, PRY
D L10 BIB AB KWIC 1-6
D L13 BIB AB KWIC 1

EAST Search History

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	2	"20040070063"	US-PGPUB ; DERWENT	OR	OFF	2009/04/21 11:42
L2	926149	((integrated near2 circuit\$4) or IC or ((circuit\$3 or wire or wiring) near2 board\$2) or (printed near2 (circuit\$4 or board\$2)) Or PCB or PWB or PCA or motherboard)	FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/04/21 11:51
L3	63122	(U24-G03E or U24-G04A or U13-B or U13-C04D or U13-D\$)	FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/04/21 11:51
L4	30253	(first or one or 1st or primary or second or two or 2nd or other or secondary) near4 (substrate\$2 or surface\$2 or membrane\$2 or wafer\$2 or chip\$2 or microchip\$2 or die or dies or dice\$3) near4 (thick\$4 or thin\$4 or slim or size\$2)	FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/04/21 11:52
L5	2492	(L2 or L3) and L4	FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/04/21 11:53
L6	900	L5 and (substrate\$2 near4 (thick\$4 or thin\$4))	FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/04/21 11:53
L7	98	L5 and (substrate\$2 near4 (thick\$4 or thin\$4) near4 (twice or double or two or half or twofold\$2))	FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/04/21 11:54
L8	0	L5 and (substrate\$2 near4 (thick\$4 or thin\$4) near4 (twice or double or two or half or twofold\$2))	US-PGPUB ; USPAT	OR	ON	2009/04/21 12:21
L9	7531	{substrate\$2 near4 (thick\$4 or thin\$4) near4 (twice or double or two or half or twofold\$2))	US-PGPUB ; USPAT	OR	ON	2009/04/21 12:22

EAST Search History

L10	3810	(substrate\$2 near4 (thick\$4 or thin\$4) near4 (twice or double or two or half or twofold\$2) near4 (first or one or 1st or primary or second or two or 2nd or other or secondary))	US-PGPUB ; USPAT	OR	ON	2009/04/21 12:22
L11	776	(substrate\$2 near4 (thick\$4 or thin\$4) near4 (twice or double or two or half or twofold\$2) near4 (first or one or 1st or primary) near4 (second or two or 2nd or other or secondary))	US-PGPUB ; USPAT	OR	ON	2009/04/21 12:23
L12	246	L11 and (@prad<"19970404" @rlad<"19970404" @ad<"19970404")	US-PGPUB ; USPAT	OR	ON	2009/04/21 12:24
L13	8	(substrate\$2 near4 (thick\$4 or thin\$4) near4 (twice or double or two or half or twofold\$2) near4 (first or one or 1st or primary or second or two or 2nd or other or secondary)) and ((overlap\$\$ or cover\$4) near5 surface\$3 near5 substrate\$2 near5 (major\$4 or most\$4))	US-PGPUB ; USPAT	OR	ON	2009/04/21 14:18
L14	272	((overlap\$\$ or cover\$4) near5 surface\$3 near5 substrate\$2 near5 (major\$4 or most\$4) near5 (first or primary or second or secondary))	US-PGPUB ; USPAT	OR	ON	2009/04/21 14:21
L15	108	L14 and (@prad<"19970404" @rlad<"19970404" @ad<"19970404")	US-PGPUB ; USPAT	OR	ON	2009/04/21 14:21
L16	38	((overlap\$\$ or cover\$4) near5 surface\$3 near5 substrate\$2 near5 (major\$4 or most\$4) near5 (first or primary or second or secondary))	FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/04/21 14:35